Ultra-Low Power, AT Command / API Controlled, Sigfox[®] Compliant Transceiver IC for Up-Link and Down-Link



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OVERVIEW

Circuit Description

AX-SFUS and AX-SFUS-API are ultra-low power single chip solutions for a node on the Sigfox network with both up- and down-link functionality. The AX-SFUS chip is delivered fully ready for operation and contains all the necessary firmware to transmit and receive data from the Sigfox network in the US (SIGFOX RCZ2 region). It connects to the customer product using a logic level RS232 UART. AT commands are used to send frames and configure radio parameters.

The AX-SFUS-API variant is intended for customers wishing to write their own application software based on the AX-SF-LIB-1-GEVK library.

Features

Functionality and Ecosystem

- Sigfox up-link and down-link functionality controlled by AT commands or API
- The AX-SFUS and AX-SF-API ICs are part of a whole development and product ecosystem available from ON Semiconductor for any Sigfox requirement. Other parts of the ecosystem include
 - Ready to go development kit DVK-SFEU-[API]-1-GEVK including a 2 year Sigfox subscription
 - ◆ Sigfox Ready[®] certified reference design for the AX–SFUS and AX–SFUS–API ICs

General Features

- QFN40 5 mm x 7 mm package
- Supply range $2.7 \text{ V}^* 3.6 \text{ V}$
- -40°C to 85°C
- Temperature sensor
- Supply voltage measurements

*Includes the RF frontend module, circuit as in Figure 5. The AX-SFUS chip alone is operational from 1.8 V to 3.6 V, a supply voltage below 2.0 V is considered an extreme condition.

• 8 GPIO pins

- ◆ 2 GPIO pins with selectable voltage measure functionality, differential (1 V or 10 V range) or single ended (1 V range) with 10 bit resolution
- 2 GPIO pins with selectable sigma delta DAC output functionality
- 2 GPIO pins with selectable output clock
- 3 GPIO pins selectable as SPI master interface
- RX/TX switching Control

Power Consumption**

- Ultra-low Power Consumption:
 - Charge required to send a Sigfox OOB packet at 24 dBm output power: 0.28 C
 - Deepsleep mode current: 100 nA
 - Sleep mode current: 1.3 μA
 - Standby mode current: 0.5 mA
 - Continuous radio RX-mode at 905.2 MHz : 34 mA
 - ◆ Continuous radio TX-mode at 902.2 MHz 230 mA @ 24 dBm

High Performance Narrow-band Sigfox RF Transceiver

- Receiver
 - Carrier frequency 905.2 MHz
 - Data-rate 600 bps FSK
 - Sensitivity
 - -128 dBm @ 600 bps, 905.2 MHz, GFSK
 - 0 dBm maximum input power
- Transmitter
 - Carrier frequency 902.2 MHz
 - Data-rate 600 bps PSK
 - High efficiency, high linearity integrated power amplifier
 - Maximum output power 24 dBm

Applications

Sigfox networks up-link and down-link.

^{**}Includes the RF frontend module, circuit as in Figure 5.

BLOCK DIAGRAM

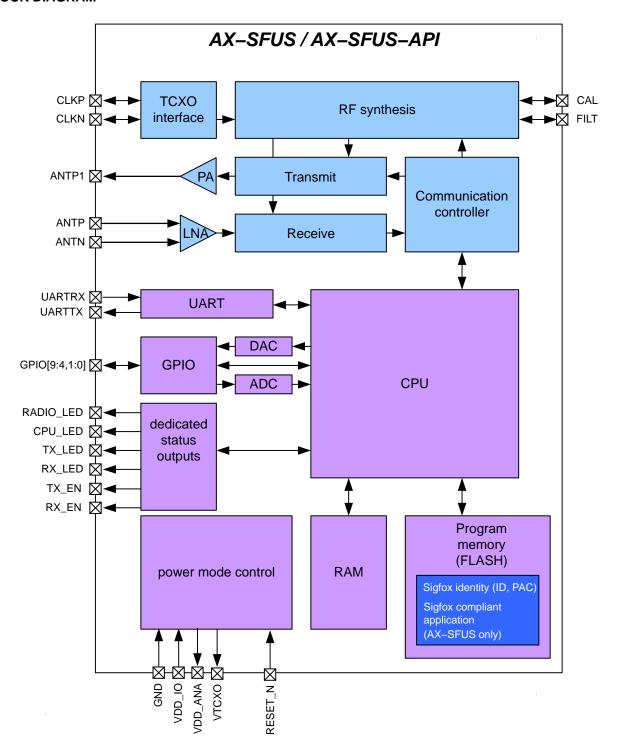


Figure 1. Functional Block Diagram of the AX-SFUS / AX-SFUS-API

Table 1. PIN FUNCTION DESCRIPTIONS

Symbol	Pin(s)	Туре	Description
VDD_ANA	1	Р	Analog power output, decouple to neighboring GND
GND	2	Р	Ground, decouple to neighboring VDD_ANA
ANTP	3	А	Differential receive input
ANTN	4	А	Differential receive input
ANTP1	5	N	Single ended transmit output
GND	6	Р	Ground, decouple to neighboring VDD_ANA
VDD_ANA	7	Р	Analog power output, decouple to neighboring GND
GND	8	Р	Ground
FILT	9	А	Synthesizer filter
L2	10	А	Must be connected to pin L1
L1	11	А	Must be connected to pin L2
NC	12	N	Do not connect
GPIO8	13	I/O/PU	General purpose IO
GPIO7	14	I/O/PU	General purpose IO, selectable SPI functionality (MISO)
GPIO6	15	I/O/PU	General purpose IO, selectable SPI functionality (MOSI)
GPIO5	16	I/O/PU	General purpose IO, selectable SPI functionality (SCK)
GPIO4	17	I/O/PU	General purpose IO, selectable $\Sigma\Delta$ DAC functionality, selectable dock functionality
CPU_LED	18	0	CPU activity indicator
RADIO_LED	19	0	Radio activity indicator
VTCXO	20	0	TCXO power
GPIO9	21	I/O/PU	General purpose IO, wakeup from deep sleep
UARTTX	22	0	UART transmit
UARTRX	23	I/PU	UART receive
RX_LED	24	0	Receive activity indicator
TX_LED	25	0	Transmit activity indicator
NC	26	PD	Do not connect
RESET_N	27	I/PU	Optional reset pin. Internal pull–up resistor is permanently enabled, nevertheless it is recommended to connect this pin to VDD_IO if it is not used.
GND	28	Р	Ground
VDD_IO	29	Р	Unregulated power supply
GPIO0	30	I/O/A/PU	General purpose IO, selectable ADC functionality, selectable $\Sigma\Delta$ DAC functionality, selectable clock functionality
GPIO1	31	I/O/A/PU	General purpose IO, selectable ADC functionality
TX_EN	32	0	Transmitter Enable (to frontend)
NC	33	N	Do not connect
NC	34	N	Do not connect
RX_EN	35	0	Receiver Enable (to frontend)
VDD_IO	36	Р	Unregulated power supply
CAL	37	А	Connect to FILT as shown in the application diagram
NC	38	N	Do not connect
CLKN	39	А	TCXO interface

Table 1. PIN FUNCTION DESCRIPTIONS

Symbol	Pin(s)	Туре	Description	
CLKP	40	Α	TCXO interface	
GND	Center pad	Р	Ground on center pad of QFN, must be connected	

A = analog input

I = digital input signal

O = digital output signal

PU = pull-up

I/O = digital input/output signal

N = not to be connected

P = power or ground

PD = pull-down

All digital inputs are Schmitt trigger inputs, digital input and output levels are LVCMOS/LVTTL compatible. Pins GPIO[3:0] must not be driven above VDD_IO, all other digital inputs are 5 V tolerant. All GPIO pins and UARTRX start up as input with pull—up. For explanations on how to use the GPIO pins, see chapter "AT Commands".

Table 2.

Pin	Possible GPIO Modes
GPIO0	0, 1, Z, U, A, T
GPIO1	0, 1, Z, U, A
GPIO4	0, 1, Z, U, T
GPIO5	0, 1, Z, U
GPIO6	0, 1, Z, U
GPIO7	0, 1, Z, U
GPIO8	0, 1, Z, U
GPIO9	0, 1, Z, U

0 = pin drives

1 = not to be connected

Z = pin is high impedance input

U = pin is input with pull-up

A = pin is analog input

T = pin is driven by clock or DAC

Pinout Drawing

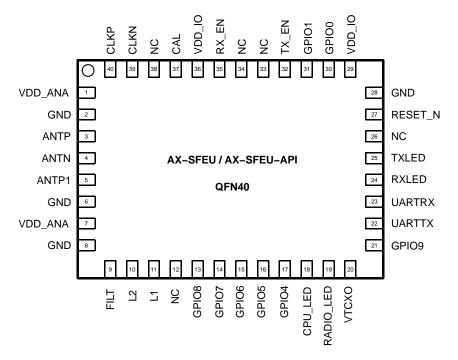


Figure 2. Pinout Drawing (Top View)

SPECIFICATIONS

Table 3. ABSOLUTE MAXIMUM RATINGS

Symbol	Description	Condition	Min	Max	Units
VDD_IO	Supply voltage		-0.5	5.5	V
IDD	Supply current			200	mA
P _{tot}	Total power consumption			800	mW
P _i	Absolute maximum input power at receiver input ANTP and ANTN pins in RX mode			10	dBm
I _{I1}	DC current into any pin except ANTP, ANTN, ANTP1		-10	10	mA
I _{I2}	DC current into pins ANTP, ANTN, ANTP1		-100	100	mA
Io	Output Current			40	mA
V _{ia}	Input voltage ANTP, ANTN, ANTP1 pins		-0.5	5.5	V
	Input voltage digital pins		-0.5	5.5	V
V _{es}	Electrostatic handling	НВМ	-2000	2000	V
T _{amb}	Operating temperature		-40	85	°C
T _{stg}	Storage temperature		-65	150	°C
Tį	Junction Temperature			150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC Characteristics

Table 4. SUPPLIES

Conditions for all current and charge values unless otherwise specified are for the hardware configuration described in the AX–SFUS Application Note: Sigfox Compliant Reference Design.

Symbol	Description	Condition	Min	Тур	Max	Units
T _{AMB}	Operational ambient temperature		-40	27	85	°C
VDD _{IO}	I/O and voltage regulator supply voltage AX–SFUS chip only		1.8*	3.0	3.6	V
VDD _{IO_mod}	I/O and voltage regulator supply voltage AX–SFUS with RF frontend module as in Figure 5		2.7	3.3	3.6	V
VDD _{IO_R1}	I/O voltage ramp for reset activation; Note 1	Ramp starts at VDD_IO ≤ 0.1 V	0.1			V/ms
VDD _{IO_R2}	I/O voltage ramp for reset activation; Note 1	Ramp starts at 0.1 V < VDD_IO < 0.7 V	3.3			V/ms
I _{DS}	Deep sleep mode current; Note 3	AT\$P=2		350		nA
I _{SLP}	Sleep mode current; Note 3	AT\$P=1		1.6		μΑ
I _{STDBY}	Standby mode current Notes 2, 3			0.5		mA
I _{RX_CONT}	Current consumption continuous RX; Note 3	AT\$TM=3,255		34		mA
Q _{SFX_OOB_24}	Charge to send a Sigfox out of band message, 24 dBm; Note 3	AT\$S0		0.25		С
Q _{SFX_BIT_24}	Charge to send a bit, 24 dBm; Note 3	AT\$SB=0		0.22		С
Q _{SFX_BITDL_24}	Charge to send a bit with downlink receive, 24 dBm; Note 3	AT\$SB=0,1		0.28		С
Q _{SFX_LFR_24}	Charge to send the longest possible Sigfox frame (12 byte) , 24 dBm; Note 3	AT\$SF=00112233445566778899aabb		0.73		С
Q _{SFX_LFRDL_24}	Charge to send the longest possible Sigfox frame (12 byte) with downlink receive, 24 dBm; Note 3	AT\$SF=00112233445566778899aabb,1		0.84		С
I _{TXMOD24AVG}	Modulated Transmitter Current; Note 3	Pout=24 dBm; average		230		mA

^{*}The device is operational from 1.8 V to 3.6 V. However, a supply voltage below 2.0 V is considered an extreme condition and operation can lead to reduced output power and increased spurious emission.

^{1.} If VDD_IO ramps cannot be guaranteed, an external reset circuit is recommended, see the AX8052 Application Note: Power On Reset

^{2.} Internal 20 MHz oscillator, voltage conditioning and supervisory circuit running.

^{3.} Includes Front End Module, TCXO.

Typical Current Waveform

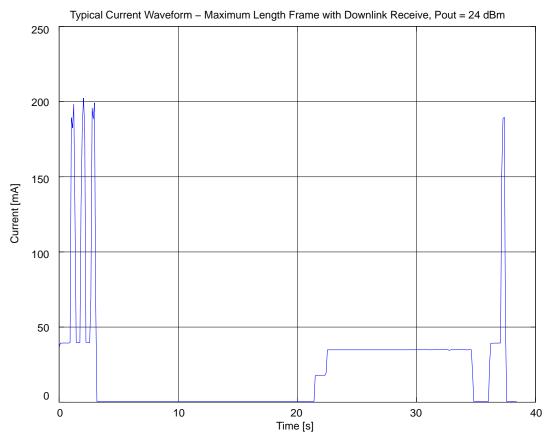


Figure 3. Typical Current Waveform for a Maximum Length Frame with Downlink Receive at 24 dBm Output Power

Battery Life Examples

Scenario:

- 2 AAA Alkaline batteries in series
- One OOB frame transmitter per day at Pout=24 dBm
- Four maximum length frames with downlink receive per day at Pout=24 dBm
- Device in Sleep
- Neglecting battery self discharge

2 AAA alkaline capacity	1500 mAh * 3600 s/h	5400 C
Sleep charge per day	1.6 μA * 86400 s	0.14 C/day
OOB frame transmission		0.25 C/day
Frame transmission with downlink	4 * 0.84 C/day	3.36 C/day
Total Charge consumption		3.75 C/day
Battery life		3.9 Years

Table 5. LOGIC

Symbol	Description	Condition	Min	Тур	Max	Units
Digital Inpu	ts		•		•	
V _{T+}	Schmitt trigger low to high threshold point	VDD_IO = 3.3 V		1.55		V
V _T	Schmitt trigger high to low threshold point			1.25		V
V _{IL}	Input voltage, low				0.8	V
V _{IH}	Input voltage, high		2.0			V
V _{IPA}	Input voltage range, GPIO[3:0]		-0.5		VDD_IO	V
V _{IPBC}	Input voltage range, GPIO[9:4], UARTRX		-0.5		5.5	V
IL	Input leakage current		-10		10	μΑ
R _{PU}	Programmable Pull–Up Resistance			65		kΩ
Digital Outp	outs					•
I _{OH}	Output Current, high Ports GPIO[9:0], UARTTX, TXLED, RXLED, TXLED, CPULED	V _{OH} = 2.4 V	8			mA
l _{OL}	Output Current, low GPIO[9:0], UARTTX, TXLED, RXLED, TXLED, CPULED	V _{OL} = 0.4 V	8			mA
I _{OZ}	Tri-state output leakage current		-10		10	μΑ

AC Characteristics

Table 6. TCXO REFERENCE INPUT

Symbol	Description	Condition	Min	Тур	Max	Units
f _{TCXO}	TCXO frequency	A passive network between the TCXO output and the pins CLKP and CLKN is required.		48		MHz
		For detailed TCXO network recommendations depending on the TCXO output swing refer to the AX5043 Application Note: Use with a TCXO Reference Clock.				
		For TCXO recommendations see the AX–SFUS Application Note: Sigfox Compliant Reference Design				

Table 7. TRANSMITTER

Conditions for transmitter specifications unless otherwise specified with the antenna network from AX–SFUS Application Note: Sigfox Compliant Reference Design and at 902.2 MHz.

Symbol	Description	Condition	Min	Тур	Max	Units
SBR	Signal bit rate			100		bps
PTX	Highest Transmitter output power	AT\$CW=902200000,1,24		24		dBm
dTX _{temp}	Transmitter power variation vs. temperature	-40°C to +85°C		±0.5		dB
dTX _{Vdd}	Transmitter power variation vs. VDD_IO	1.8 to 3.6 V		±0.5		dB
PTX _{harm2}	Emission @ 2 nd harmonic			-51		dBc
PTX _{harm3}	Emission @ 3 rd harmonic]		-63		
PTX _{harm4}	Emission @ 4 th harmonic			-84		

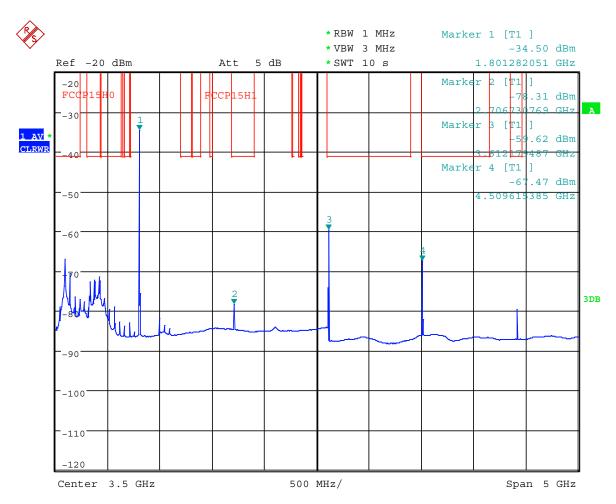


Figure 4. Typical Spectrum with Harmonics at 24 dBm Output Power

Table 8. RECEIVER

Conditions for transmitter specifications unless otherwise specified with the antenna network from AX–SFUS Application Note: Sigfox Compliant Reference Design and at 869.525 MHz.

Symbol	Description	Condition	Min	Тур	Max	Units
SBR	Signal bit rate			600		bps
IS _{BER868}		AT\$SB=x,1, AT\$SF=x,1, AT\$TM=3,x PER < 0.1		-128		dBm
BLK ₉₀₅	Blocking at ±10 MHz offset	Channel/Blocker @ PER = 0.1, wanted signal level is +3 dB above the typical sensitivity, the blocker signal is CW		78		dB

Table 9. ADC / TEMPERATURE SENSOR

Symbol	Description	Condition	Min	Тур	Max	Units		
ADCRES	ADC resolution			10		Bits		
V _{ADCREF}	ADC reference voltage		0.95	1	1.05	V		
Z _{ADC00}	Input capacitance				2.5	pF		
DNL	Differential nonlinearity			± 1		LSB		
INL	Integral nonlinearity			± 1		LSB		
OFF	Offset			3		LSB		
GAIN_ERR	Gain error			0.8		%		
ADC in Differ	ential Mode							
V _{ABS_DIFF}	Absolute voltages & common mode voltage in differential mode at each input		0		VDD_IO	V		
V _{FS_DIFF01}	Full swing input for differential signals	Gain x1	-500		500	mV		
V _{FS_DIFF10}		Gain x10	-50		50	mV		
ADC in Singl	e Ended Mode	•			•	•		
V _{MID_SE}	Mid code input voltage in single ended mode			0.5		V		
V _{IN_SE00}	Input voltage in single ended mode		0		VDD_IO	V		
V _{FS_SE01}	Full swing input for single ended signals	Gain x1	0		1	V		
Temperature	Temperature Sensor							
T _{RNG}	Temperature range	AT\$T?	-40		85	°C		
T _{ERR_CAL}	Temperature error	AT\$T?	-2		2	°C		

COMMAND INTERFACE

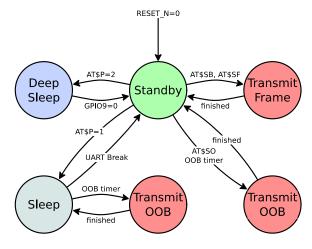
General Information

The chapter "Command Interface" is a documentation of the AT-Command set for devices which do not have an API-interface. To see whether the device is capable of receiving AT-Commands, please refer to chapter "Part Numbers". If the device has been shipped with the API-Interface, please refer to the SW manual and "apiexample" code delivered with AX-SF-LIB-1-GEVK for an introduction on how to setup a project and how to use the API-Interface.

Serial Parameters: 9600, 8, N, 1

The AX-SFUS uses the UART (pins UARTTX, UARTRX) to communicate with a host and uses a bitrate of **9600 baud**, no parity, 8 data bits and one stop bit.

Power Modes



Standby

After Power–Up and after finishing a SIGFOX transmission, AX–SFUS enters Standby mode. In Standby mode, AX–SFUS listens on the UART for commands from the host. Also, OOB frames are transmitted whenever the OOB timer fires. To conserve power, the AX–SFUS can be put into Sleep or turned off (Deep Sleep) completely.

Sleep

The command AT\$P=1 is used to put the AX-SFUS into Sleep mode. In this mode, only the wakeup timer for out-of-band messages is still running. To wake the AX-SFUS up from Sleep mode toggle the serial UARTRX pin, e.g. by sending a break (break is an RS232 framing violation, i.e. at least 10 bit durations low). When an Out of Band (OOB) message is due, AX-SFUS automatically wakes up to transmit the message, and then returns to Sleep mode.

Deep Sleep

In Deep Sleep mode, the AX-Sigfox is completely turned off and only draws negligible leakage current. Deep Sleep

mode can be activated with AT\$P=2. To wake-up from Deep Sleep mode, GPIO9 is pulled to GND.

When using Deep Sleep mode, keep two things in mind: Everything is turned off, timers are not running at all and all settings will be lost (use **AT\$WR** to save settings to flash before entering Deep Sleep mode). Out–of–band messages will therefore not be sent. The pins states are frozen in Deep Sleep mode. The user must ensure that this will not result in condition which would draw a lot of current.

AT Commands

Numerical Syntax

```
hexdigit ::= [0-9A-Fa-f]
hexnum ::= "0x" hexdigit+
decnum ::= "0" | [1-9] [0-9]*
octnum ::= "0" [0-7]+
binnum ::= "0b" [01]+
bit ::= [01]
optnum ::= "-1"
frame ::= (hexdigit hexdigit)+
uint ::= hexnum | decnum | octnum |
```

uint ::= hexnum | decnum | octnum | binnum

uint_opt ::= uint | optnum

Command Syntax

A command starts with 'AT' (everything is case sensitive!), continues with the actual command followed by parameters (if any) and ends with any kind of whitespace (space, tab, newline etc.)

If incorrect syntax is detected ("parsing error") all input is ignored up until the next whitespace character.

Also note that any number can be entered in any format (Hexadecimal, Decimal, Octal and binary) by adding the corresponding prefix ('0x', '0', '0b'). The only exception is the 'Send Frame' command (AT\$SF) which expects a list of hexadecimal digits without any prefix.

Return Codes

A successful command execution is indicated by sending 'OK'. If a command returns a value (e.g. by querying a register) only the value is returned.

Examples

Bold text is sent to AX-SFUS.

AT\$I=0

AXSEM AT Command Interface

Here, we execute command 'I' to query some general information.

AT\$SF=aabb1234

OK

This sends a Sigfox frame containing { 0x00:0x11:0x22:0x33:0x44 }, then waits for a downlink response telegram, which in this example contains { 0xAA:0xBB:0xCC:0xDD }.

AT\$CB=0011223344,1

OK

RX=AA BB CC DD

This sends a Sigfox frame containing { 0xAA:0xBB:0x12:0x34 } without waiting for a response telegram.

AT\$CB=0xAA,1

OK

The 'CB' command sends out a continuous pattern of bits, in this case 0xAA = 0b10101010.

AT\$P=1

OK

This transitions the device into sleep mode. Out-of-band transmissions will still be triggered. The UART is powered down. The device can be woken up by a low level on the UART signal, i.e. by sending break.

Table 10. COMMANDS

Command	Name			Description			
AT	Dummy Command		Just returns 'OK' and does nothing else. Can be used to check communication.				
AT\$SB=bit[,bit]	Send Bit	Send a bit st should recei	Send a bit status (0 or 1). Optional bit flag indicates if AX–SFUS should receive a downlink frame.				
AT\$SF=frame[,bit]	Send Frame		d data, 1 to 12 by	ytes. Optional bit flag indicates if lownlink frame.			
AT\$SO	Manually send out of band message	Send the out	t-of-band messa	age.			
AT\$TR?	Get the transmit repeat	Returns the	number of transn	nit repeats. Default: 2			
AT\$TR=?	Get transmit range	Returns the	allowed range of	transmit repeats.			
AT\$TR=uint	Get transmit repeat	Sets the tran	nsmit repeat.				
ATSuint?	Get Register	Query a spe "Registers" f	cific configuration or a list of registe	n register's value. See chapter ers.			
ATSuint=uint	Set Register	Change a co	onfiguration regis	ter.			
ATSuint=?	Get Register Range	Returns the	allowed range of	transmit repeats.			
AT\$IF=uint	Set TX Frequency	Set the outp	ut carrier macro	channel for Sigfox frames.			
AT\$IF?	Get TX Frequency	Get the curre	ently chosen TX t	frequency.			
AT\$DR=uint	Set RX Frequency	Set the rece	ption carrier mac	ro channel for Sigfox frames.			
AT\$DR?	Get RX Frequency	Get the curre	ently chosen RX	frequency.			
AT\$CW=uint,bit[,uint_opt]	Continuous Wave		vave, i.e. just the	ox certification it is necessary to send a base frequency without any modula-			
		Name	Range	Description			
		Frequency	800000000- 999999999, 0	Continuous wave frequency in Hz. Use 902200000 for Sigfox or 0 to keep previous frequency.			
		Mode	0, 1	Enable or disable carrier wave.			
		Power	24	dBm of signal Default: 24			
AT\$CB=uint_opt,bit	Test Mode: TX constant byte	first paramet		ful to send a specific bit pattern. The byte to send. Use '-1' for a grameters:			
		Name	Range	Decsription			
		Pattern	0–255, –1	Byte to send. Use '-1' for a (pseudo-)random pattern.			
		Mode	0, 1	Enable or disable pattern test mode.			
AT\$RC	Reset FCC Macrochannel	This command resets the FCC Macrochannel. Subsequent transmit operations (AT\$SO, AT\$SB, AT\$SF) may pause up to 20 s to ensure FCC compliance					
AT\$T?	Get Temperature	Measure inte	ernal temperature	e and return it in 1/10 th of a degree			

Table 10. COMMANDS

Command	Name	Description		
AT\$V?	Get Voltages	Return current voltage and voltage measured during the last transmission in mV.		
AT\$I=uint	Information	Display various product information: 0: Software Name & Version Example Response: AX–Sigfox 1.1.1–FCC 1: Contact Details Example Response: support@axsem.com 2: Silicon revision lower byte Example Response: 8F 3: Silicon revision upper byte Example Response: 51 4: Major Firmware Version Example Response: 1 5: Minor Firmware Version Example Response: 1 7: Firmware Variant (Frequency Band etc. (EU/US)) Example Response: FCC 9: SIGFOX Library Version Example Response: UDL1–1.8.7 10: Device ID Example Response: 00012345 11: PAC Example Response: 0123456789ABCDEF		
AT\$P=uint	Set Power Mode	To conserve power, the AX–SFUS can be put to sleep manually. Depending on power mode, you will be responsible for waking up the AX–SFUS again! 0: software reset (settings will be reset to values in flash) 1: sleep (send a break to wake up) 2: deep sleep (toggle GPIO9 or RESET_N pin to wake up; the AX–SFUS is not running and all settings will be reset!)		
AT\$WR	Save Config	Write all settings to flash (RX/TX frequencies, registers) so they survive reset/deep sleep or loss of power. Use AT\$P=0 to reset the AX-SFUS and load settings from flash.		
AT:Pn?	Get GPIO Pin	Return the setting of the GPIO Pin <i>n</i> ; <i>n</i> can range from 0 to 9. A character string is returned describing the mode of the pin, followed by the actual value. If the pin is configured as analog pin, then the voltage (range 01 V) is returned. The mode characters have the following meaning: Mode Description O Pin drives low 1 Pin drives high 2 Pin is high impedance input U Pin is input with pull–up A Pin is analog input (GPIO pin 03 only) T Pin is driven by clock or DAC (GPIO pin 0 and 4 only) The default mode after exiting reset is U on all GPIO pins.		
AT:Pn=?	Get GPIO Pin Range	Print a list of possible modes for a pin. The table below lists the response. Pin Modes P0 0, 1, Z, U, A, T P1 0, 1, Z, U, A P4 0, 1, Z, U, T P5 0, 1, Z, U P6 0, 1, Z, U P7 0, 1, Z, U P8 0, 1, Z, U P9 0, 1, Z, U		
AT:Pn=mode	Set GPIO Pin	Set the GPIO pin mode. For a list of the modes see the command AT:Pn?		

Table 10. COMMANDS

Command	Name	Description		
AT:ADC Pn[-Pn[(1V 10V)]]?	Get GPIO Pin Analog Voltage	Measure the voltage applied to a GPIO pin. The command also allows measurement of the voltage difference across two GPIO pins. In differential mode, the full scale range may also be specified as 1 V or 10 V. Note however that the pin input voltages must not exceed the range 0VDD_IO. The command returns the result as fraction of the full scale range (1 V if none is specified). The GPIO pins referenced should be initialized to analog mode before issuing this command.		
AT:SPI[(A B C D)]=bytes	SPI Transaction	This command clocks out <i>bytes</i> on the SPI port. The clock frequency is 312.5 kHz. The command returns the bytes read on MISO during output. Optionally the clocking mode may be specified (default is A):		
		Mode Clock Inversion Clock Phas	se	
		A normal normal B normal alternate C inverted normal D inverted alternate		
ATOLIK from neffrom	Set Clark Consists	SEL (GPIOx) MOSI	commands	
AT:CLK=freq,reffreq	Set Clock Generator	Output a square wave on the pin(s) set to T mode. T the square wave is (freq / 2^{16}) × reffreq. Possible val are 20000000, 10000000, 5000000, 2500000, 12500 312500, 156250. Possible values if freq are 06553	ues for reffreq 000, 625000,	
AT:CLK=OFF	Turn off Clock Generator	Switch off the clock generator		
AT:CLK?	Get Clock Generator	Return the settings of the clock generator. Two number returned, freq and reffreq.	pers are	
AT:DAC=value	Set $\Sigma\Delta$ DAC	Output a $\Sigma\Delta$ DAC value on the pin(s) set to T mode. value may be in the range -3276832767 . The average is $(1/2 + \text{value} / 2^{17}) \times \text{VDD}$. An external low pass filter is needed to get smooth of The modulation frequency is 20 MHz. A possible low choice is a simple RC low pass filter with R = $10 \text{ k}\Omega$	rage output utput voltages. pass filter	
AT:DAC=OFF	Turn off $\Sigma\Delta$ DAC	Switch off the DAC		
AT:DAC?	Get ΣΔ DAC	Return the DAC value		

Table 10. COMMANDS

Command	Name	Description
AT\$TM=mode,config	Activates the Sigfox Testmode	Available test modes: 0. TX BPSK Send only BPSK with Synchro Bit + Synchro frame + PN sequence: No hopping centered on the TX_frequency. Config bits 0 to 6 define the number of repetitions. Bit 7 of config defines if a delay is applied of not in the loop 1. TX Protocol: Tx mode with full protocol with Sigfox key: Send Sigfox protocol frames with initiate downlink flag = True. Config defines the number of repetitions. 2. RX Protocol: This mode tests the complete downlink protocol in Downlink only. Config defines the number of repetitions. 3. RX GFSK: RX mode with known pattern with SB + SF + Pattern on RX_frequency (internal comparison with received frame ⇔ known pattern = AA AA B2 27 1F 20 41 84 32 68 C5 BA AE 79 E7 F6 DD 9B. Config defines the number of repetitions. Config defines the number of repetitions. 4. RX Sensitivity: Does uplink + downlink frame with Sigfox key and specific timings. This test is specific to SIGFOX's test equipments & softwares. 5. TX Synthesis: Does one uplink frame on each Sigfox channel to measure frequency synthesis step
AT\$SE	Starts AT\$TM-3,255 indefinitely	Convenience command for sensitivity tests
AT\$SL[=frame]	Send local loop	Sends a local loop frame with optional payload of 1 to 12 bytes. Default payload: 0x84, 0x32, 0x68, 0xC5, 0xBA, 0x53, 0xAE, 0x79, 0xE7, 0xF6, 0xDD, 0x9B.
AT\$RL	Receive local loop	Starts listening for a local loop.

Table 11. REGISTERS

Number	Name	Description	Default	Range	Units
300	Out Of Band Period	AX–SFUS sends periodic static messages to indicate that they are alive. Set to 0 to disable.	24	0–24	hours
400	Macrochannel Mask	The mask of Macrochannels to use.	<000001FF> <00000000> <00000000>,1		
410	Encryption Key Configuration	Set to zero for normal operation. Set to one for use with the SIGFOX Network Emulator Kit (SNEK)	0	0–1	0: private key 1: public key

APPLICATION INFORMATION

Typical Application Diagrams

Typical AX-SFUS/AX-SFUS-API Application Diagram

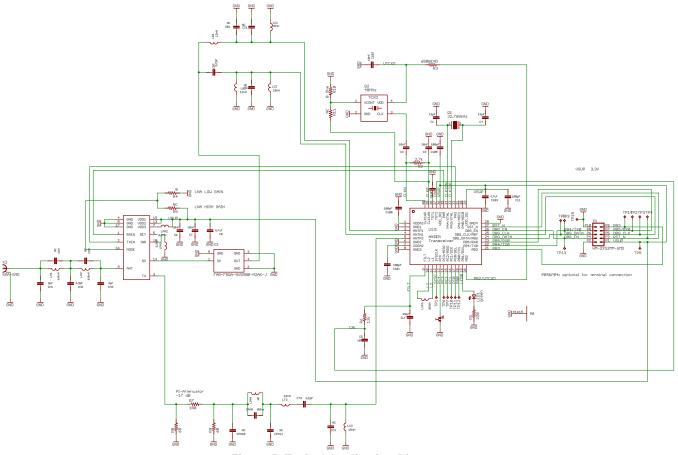


Figure 5. Typical Application Diagram

For detailed application configuration and BOM see the AX-SFUS Application Note: Sigfox Compliant Reference Design.

QFN40 Soldering Profile

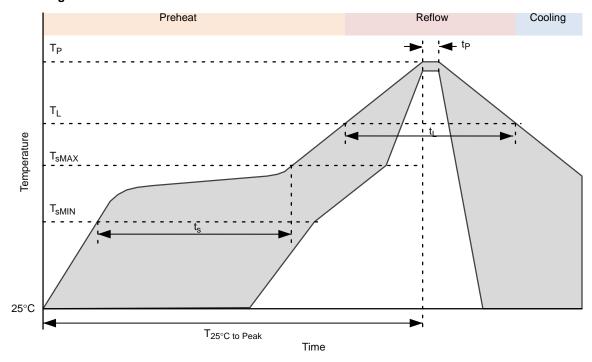


Figure 6. QFN40 Soldering Profile

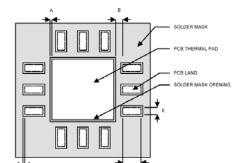
Table 12.

Profile Feature	Pb-Free Process	
Average Ramp-Up Rate		3°C/s max.
Preheat Preheat		
Temperature Min	T _{sMIN}	150°C
Temperature Max	T _{sMAX}	200°C
Time (T _{sMIN} to T _{sMAX})	t_s	60 – 180 sec
Time 25°C to Peak Temperature	T _{25°C to Peak}	8 min max.
Reflow Phase		
Liquidus Temperature	T_L	217°C
Time over Liquidus Temperature	t_L	60 – 150 s
Peak Temperature	t_p	260°C
Time within 5°C of actual Peak Temperature	T_p	20 – 40 s
Cooling Phase		
Ramp-down rate		6°C/s max.

^{1.} All temperatures refer to the top side of the package, measured on the the package body surface.

QFN40 Recommended Pad Layout

1. PCB land and solder masking recommendations are shown in Figure 7.



- A = Clearance from PCB thermal pad to solder mask opening, 0.0635 mm minimum
- B = Clearance from edge of PCB thermal pad to PCB land, 0.2 mm minimum
- C = Clearance from PCB land edge to solder mask opening to be as tight as possible to ensure that some solder mask remains between PCB pads.
- D = PCB land length = QFN solder pad length + 0.1 mm
- E = PCB land width = QFN solder pad width + 0.1 mm

Figure 7. PCB Land and Solder Mask Recommendations

- 2. Thermal vias should be used on the PCB thermal pad (middle ground pad) to improve thermal conductivity from the device to a copper ground plane area on the reverse side of the printed circuit board. The number of vias depends on the package thermal requirements, as determined by thermal simulation or actual testing.
- 3. Increasing the number of vias through the printed circuit board will improve the thermal conductivity to the reverse side ground plane and external heat sink. In general, adding more metal through the PC board under the IC will improve operational heat transfer, but will require careful attention to uniform heating of the board during assembly.

Assembly Process

Stencil Design & Solder Paste Application

- 1. Stainless steel stencils are recommended for solder paste application.
- 2. A stencil thickness of 0.125 0.150 mm (5 6 mils) is recommended for screening.

- 3. For the PCB thermal pad, solder paste should be printed on the PCB by designing a stencil with an array of smaller openings that sum to 50% of the QFN exposed pad area. Solder paste should be applied through an array of squares (or circles) as shown in Figure 8.
- 4. The aperture opening for the signal pads should be between 50–80% of the QFN pad area as shown in Figure 9.
- 5. Optionally, for better solder paste release, the aperture walls should be trapezoidal and the corners rounded.
- 6. The fine pitch of the IC leads requires accurate alignment of the stencil and the printed circuit board. The stencil and printed circuit assembly should be aligned to within + 1 mil prior to application of the solder paste.
- 7. No-clean flux is recommended since flux from underneath the thermal pad will be difficult to clean if water-soluble flux is used.

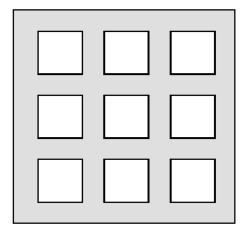


Figure 8. Solder Paste Application on Exposed Pad

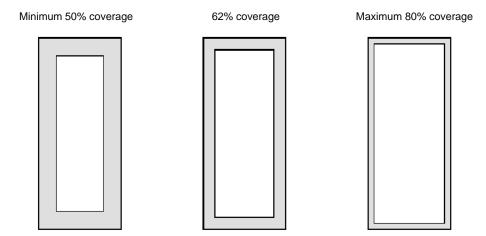


Figure 9. Solder Paste Application on Pins

Life Support Applications

This product is not designed for use in life support appliances, devices, or in systems where malfunction of this product can reasonably be expected to result in personal injury. ON Semiconductor customers using or selling this product for use in such applications do so at their own risk

and agree to fully indemnify ON Semiconductor for any damages resulting from such improper use or sale.

Device Information

The following device information can be queried using the AT-Commands AT\$I=4, AT\$I=5 for the APP version and AT\$I=2, AT\$I=3 for the chip version.

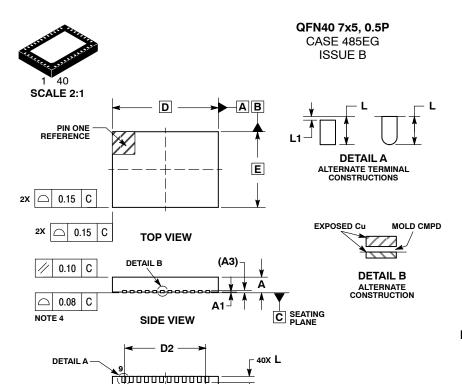
Table 13. DEVICE VERSIONS

		APP Version		Chip V	ersion
Product	Part Number	[0]	[1]	[0]	[1]
AX-SFUS	AX-SFUS-1-01-XXXX ¹	0x01	0x01	0x8F	0x51
AX-SFUS-API	AX-SFUS-API-1-01-XXXX ¹	0x01	0x01	0x8F	0x51

^{1.} TB05 for Reel 500, TX30 for Reel 3000 reel

E2

DATE 26 APR 2017



0.10 C A B

C NOTE 3

0.05

NOTES:

- NOTES:

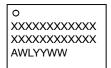
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

 2. CONTROLLING DIMENSIONS: MILLIMETERS.

 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30mm FROM TERMINAL
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS			
DIM	MIN	MAX		
Α	0.80	1.00		
A1	0.00	0.05		
A3	0.20	REF		
b	0.18	0.30		
D	7.00	7.00 BSC		
D2	5.30	5.50		
E	5.00	5.00 BSC		
E2	3.30	3.50		
е	0.50 BSC			
L	0.30	0.50		
L1		0.15		

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Assembly Location

WL = Wafer Lot

YY = Year

WW = Work Week

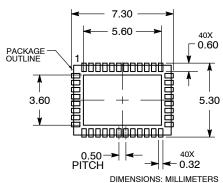
*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED SOLDERING FOOTPRINT*

BOTTOM VIEW

е

e/2



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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